

General Features

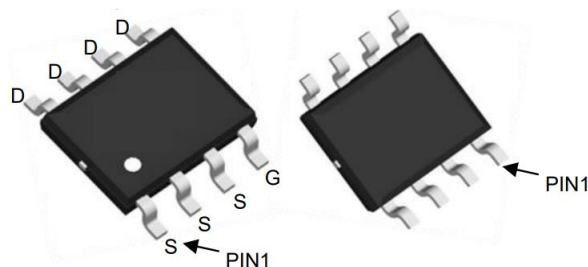
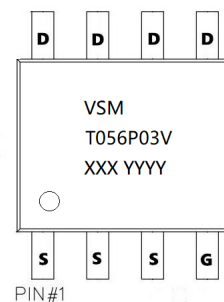
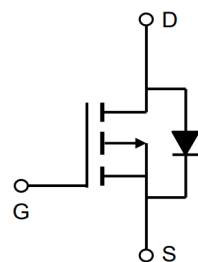
V_{DS}	I_D	$R_{DS(ON)}$ Type @ $V_{GS} = -10V$	$R_{DS(ON)}$ Type @ $V_{GS} = -4.5V$
-30V	-20A	5.6 m Ω	8.0 m Ω

Description

The VSMT056P03VA1 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Application

Lithium battery protection
Wireless impact
Mobile phone fast charging



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
VSMT056P03VA1	SOP-8L	VSM T056P03V XXX YYYY	3000

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_{D@TC=25^{\circ}C}$	Continuous Drain Current, $V_{GS} @ -10V_1$	-20	A
$I_{D@TC=100^{\circ}C}$	Continuous Drain Current, $V_{GS} @ -10V_1$	-16.8	A
I_{DM}	Pulsed Drain Current ²	-60	A
E_{AS}	Single Pulse Avalanche Energy ³	125	mJ
$P_{D@TC=25^{\circ}C}$	Total Power Dissipation ⁴	69	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient 1	85	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	1.6	$^{\circ}C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	-34	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.0232	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-20A	---	5.6	7.2	mΩ
		V _{GS} =-4.5V, I _D =-15A	---	8.0	11	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	4.6	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	-5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-30A	---	30	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	9.8	---	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-15V, V _{GS} =-4.5V I _D =-20A	---	35	---	nC
Q _{gs}	Gate-Source Charge		---	9.9	---	
Q _{gd}	Gate-Drain Charge		---	10.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-15V, V _{GS} =-10V, R _G =3.0Ω I _D =-20A	---	10.8	---	ns
T _r	Rise Time		---	13.2	---	
T _{d(off)}	Turn-Off Delay Time		---	73	---	
T _f	Fall Time		---	35	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	3520	---	pF
C _{oss}	Output Capacitance		---	465	---	
C _{rss}	Reverse Transfer Capacitance		---	370	---	
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	-70	A
I _{SM}	Pulsed Source Current		---	---	-130	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.3	V
t _{rr}	Reverse Recovery Time	I _F =-20A, dI/dt=100A/μs, T _J =25°C	---	25	---	nS
Q _{rr}	Reverse Recovery Charge		---	10	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The power dissipation is limited by 175°C junction temperature
- 4、EAS condition: T_J=25°C, V_{DD}= -24V, V_G= -10V, R_G=7Ω, L=0.1mH, I_{AS}= -40A
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

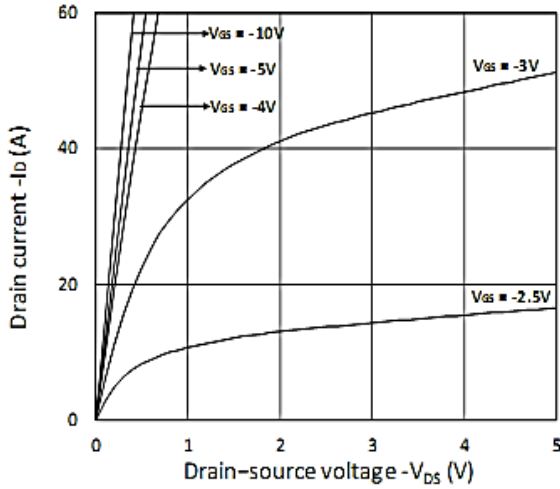


Figure 1. Output Characteristics

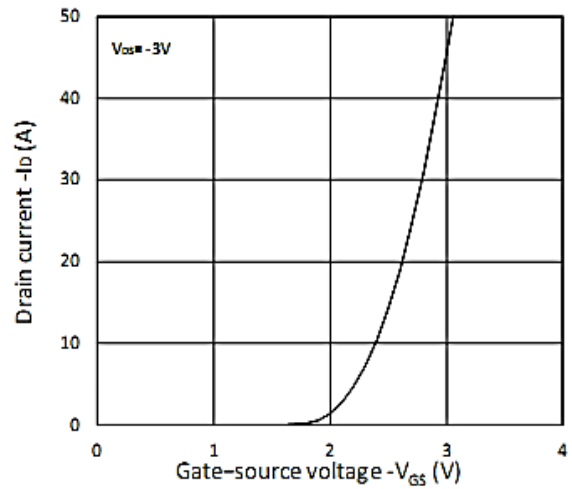


Figure 2. Transfer Characteristics

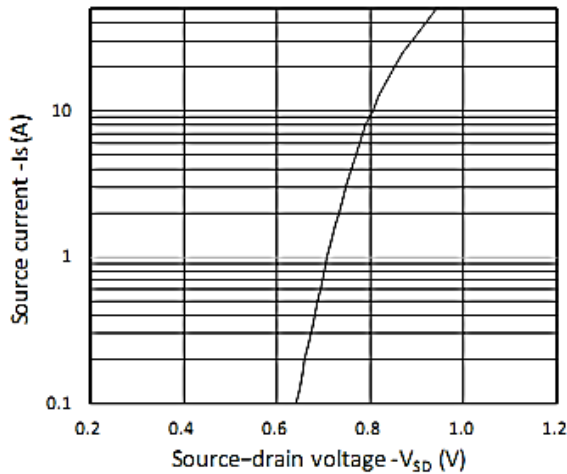


Figure 3. Forward Characteristics of Reverse

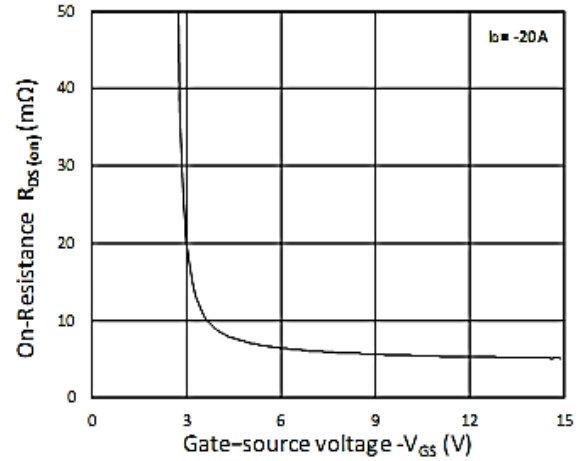


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

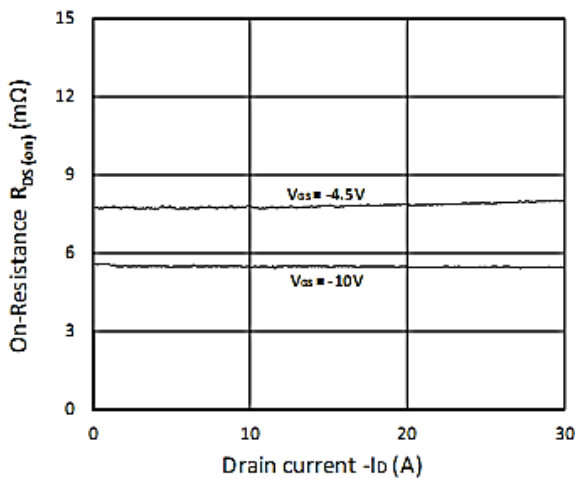


Figure 5. $R_{DS(ON)}$ vs. I_D

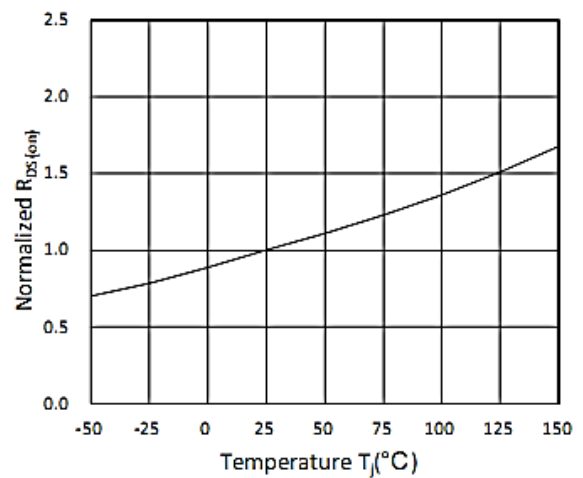


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

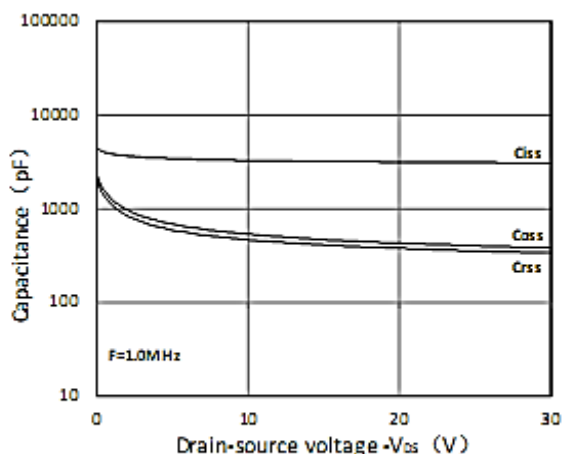


Figure 7. Capacitance Characteristics

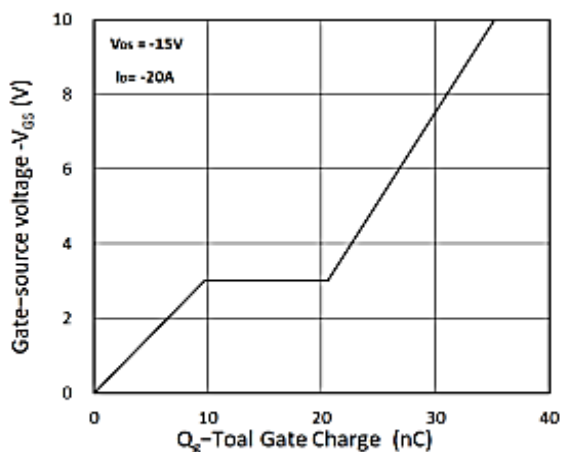


Figure 8. Gate Charge Characteristics

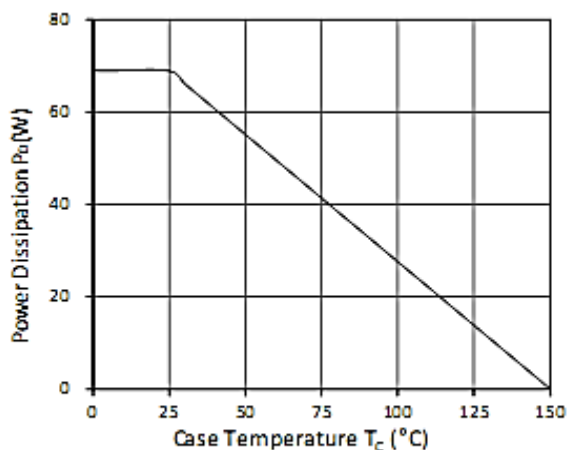


Figure 9. Power Dissipation

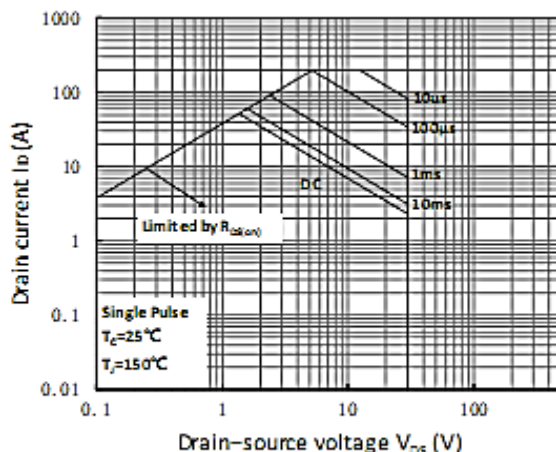


Figure 10. Safe Operating Area

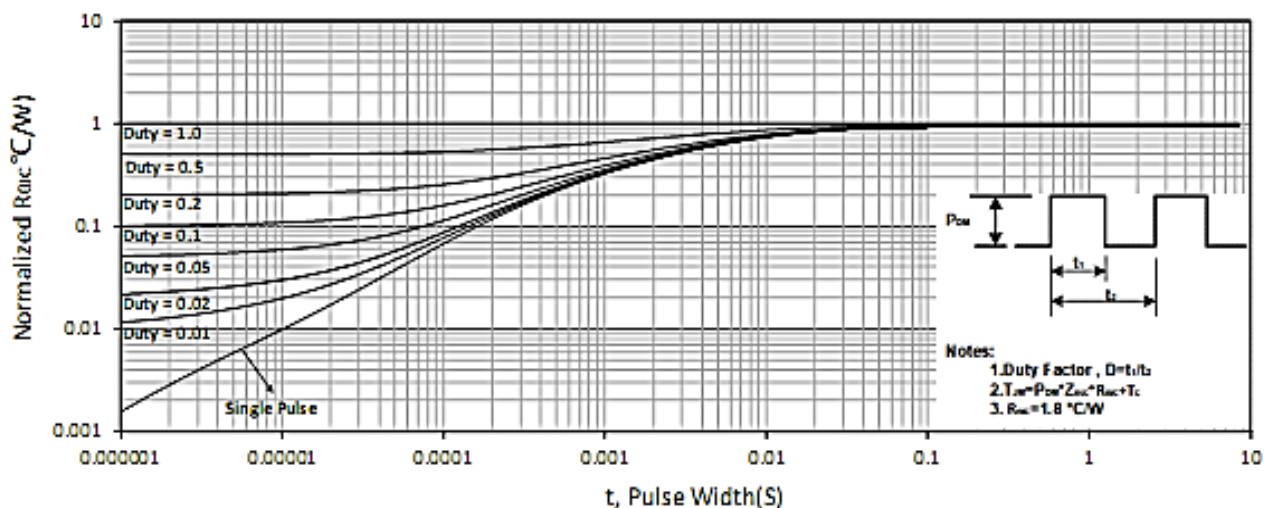
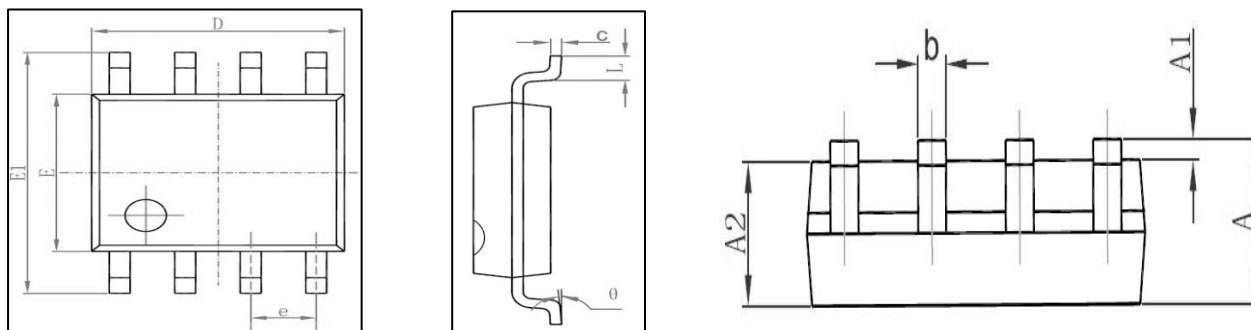
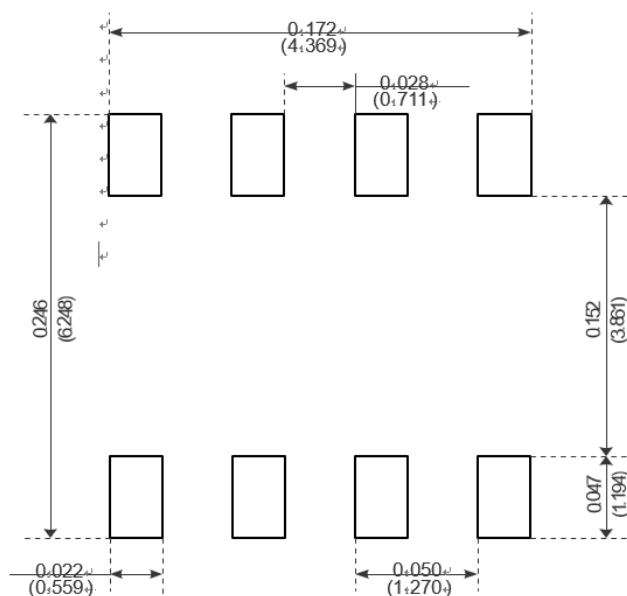


Figure 11. Normalized Maximum Transient Thermal Impedance

Package Mechanical Data-SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads